

## Venue and Accommodation

### Nagoya

Nagoya is the third leading city of Japan's major economic centers after Tokyo and Osaka. The city is highly accessible from other major cities with the Central Japan International Airport and well-developed transportation systems. Nagoya has the history of famous leading clan of Tokugawa family. The founder of Tokugawa Shogunate, Tokugawa Ieyasu, built the magnificent Nagoya Castle 400 years ago. Along with its ancient history, Nagoya is also famous for industrial tourism. The city abounds in industrial museums such as Toyota Commemorative Museum of Industry and Technology and Noritake Garden. Around the city, there are also other attractive tourist sights such as Takayama, the beautifully preserved ancient town in mountain area, and Ise-shima with the history of Mikimoto pearl culturing in bay area. Those areas could be ideal excursion destinations.

Many excellent hotels are available at **Nagoya station**, **Sakae** and **Kanayama** area in the city.

### Nagoya Congress Center

Nagoya Congress Center is the largest international congress place in Nagoya. Nearest stations are Hibino sta. and Nishi-takakura sta. on Meijo-line of Nagoya subway. It takes about 5 minutes from the stations to the center on foot.

<http://www.nagoya-congress-center.jp/english/>

### Nagoya Congress Center



# 11<sup>TH</sup> International Conference on Technology of Plasticity ICTP 2014

October 19-24, 2014  
Nagoya Congress Center  
Nagoya, Japan

## Important days

### 2013

November 30 Deadline for abstract submission  
December 31 Notification of abstract acceptance

### 2014

March 31 Deadline for submission of paper  
June 15 Notification of proceedings paper acceptance  
June 30 Deadline for author payment  
October 19-24 Conference

## Contact

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Japan Society for Technology of Plasticity



Nagoya Convention & Visitors Bureau

## About ICTP Olympics of Metal Forming

The 11th International Conference on Technology of Plasticity (ICTP 2014) will take place in Nagoya, Japan on October 19-24, 2014. It is organized by the Japan Society on Technology of Plasticity (JSTP). This triannual conference has become one of the biggest international events in forming technology. The conference will cover all major areas of materials forming and offer the chances to exchange advanced research and development information.

### History of ICTP

Tokyo, Japan (1984)	Erlangen/Nuremberg, Germany (1999)
Stuttgart, Germany (1987)	Yokohama, Japan (2002)
Kyoto, Japan (1990)	Verona, Italy (2005)
Beijing, China (1993)	Gyeongju, Korea (2008)
Columbus, OH, USA (1996)	Aachen, Germany (2011)

## Conference Topic

### Forming Process

- Bulk forming: extrusion, forging, rolling, wire and tube drawing
- Sheet forming: sheet drawing, hydroforming, roll forming, incremental forming
- Microforming
- Joining by forming
- Shearing
- Forming in high-temperature: semisolid forming, laser forming
- Thermo-mechanical processing
- Rapid prototyping
- New processes

### Technology Areas

- Optimization of process and product quality
- Machines
- Tools and dies
- Tribology, wear, coating
- Economy and ecology in forming

### Methods

- Analytical methods
- Numerical methods
- Statistical methods
- Material testing
- Optimization
- Formability, damage and failure analysis
- Material characterization
- Process control

## Committees

### Standing advisory board

#### Chairman

M. Kiuchi, Japan

#### Secretary

K. Mori, Japan

#### Members

J. Allwood, UK	P. Bariani, Italy
Y. Chastel, France	J. L. Chenot, France
M. Geiger, Germany	G. Hirt, Germany
T. Ishikawa, Japan	C. G. Kang, Korea
A. Kocanda, Poland	R. Kopp, Germany
G. Lahoti, USA	P. Martins, Portugal
K. Osakada, Japan	R. Shivpuri, USA
A. E. Tekkaya, Germany	M. Tisza, Hungary
J. Yanagimoto, Japan	D. Y. Yang, Korea
S. J. Yuan, China	

### Organizing committee

#### Chairmen

T. Ishikawa, Japan

#### Members

E. Abe, Japan	K. Mori, Japan
M. Abo, Japan	Y. Abe, Japan
S. Hiwatashi, Japan	K. Hayakawa, Japan
S. Isogawa, Japan	T. Iguchi, Japan
S. Ishihara, Japan	T. Ishiguro, Japan
N. Kanetake, Japaz	N. Iwata, Japan
K. Kawai, Japan	K. Kato, Japan
K. Komori, Japan	K. Kitamura, Japan
T. Maeno, Japan	T. Kuboki, Japan
H. Morishita, Japan	S. Maki, Japan
H. Shoji, Japan	K. Nakamura, Japan
K. Suzuki, Japan	S. Sugiyama, Japan
M. Terano, Japan	S. Tanaka, Japan
T. Yamada, Japan	Z. Wang, Japan
H. Yoshida, Japan	H. Yokoo, Japan
N. Yukawa, Japan	Y. Yoshida, Japan

## Call for paper

### Abstract submission

Paper presentations relating advanced metal forming technology are welcome. Please submit your abstract until November 30, 2013.

### Paper manuscript submission

One author can submit one proceedings paper (6 pages). Simultaneously the author can submit one optional JMPT (Journal of Materials Processing Technology) paper (8-12 pages) if he wants. The contents of the proceedings (6 pages) paper and the optional JMPT (8-12 pages) paper are similar, while the JMPT paper has enough quality to be published from international journals, sufficient results, background, originality, etc. The proceedings papers will be reviewed by members of the International Scientific Committee and, if accepted, published as proceedings. The JMPT papers will be reviewed by SAB-Sub-SC/ICTP and selected papers will be recommended to the publisher of JMPT. They will be finally reviewed by the regular procedure of JMPT, and, if accepted, published from Journal of Materials Processing Technology.

- Poster sessions will be organized in addition to the oral sessions.
- The official language is English.

## Registration fee

Regular (Early registration)*	JPY 70,000 (before June 30, 2014)
Regular (Late registration)*	JPY 80,000
Student (Early registration)*	JPY 60,000 (before June 30, 2014)
Student (Late registration)*	JPY 70,000
Accompanying person**	JPY 20,000

\* The fee will cover conference proceedings, welcome reception, conference banquet, farewell party and lunches.

\*\*The fee will cover welcome reception, conference banquet, and farewell party.